

Industrial DRAM Solutions



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What Sets Apacer Apart?

Quality Assurance

• 100% reliable & compliant

Wide temperature test Thermal shock test Strict ORT (Ongoing Reliability Test) Humidity test Altitude test Reliability test (Vibration/Shock)

Extensive Experience

- Tier 1 industrial SSD & memory supplier; delivered over 352 million units
- Comprehensive experience in product customization (across industries)

Reliable Service

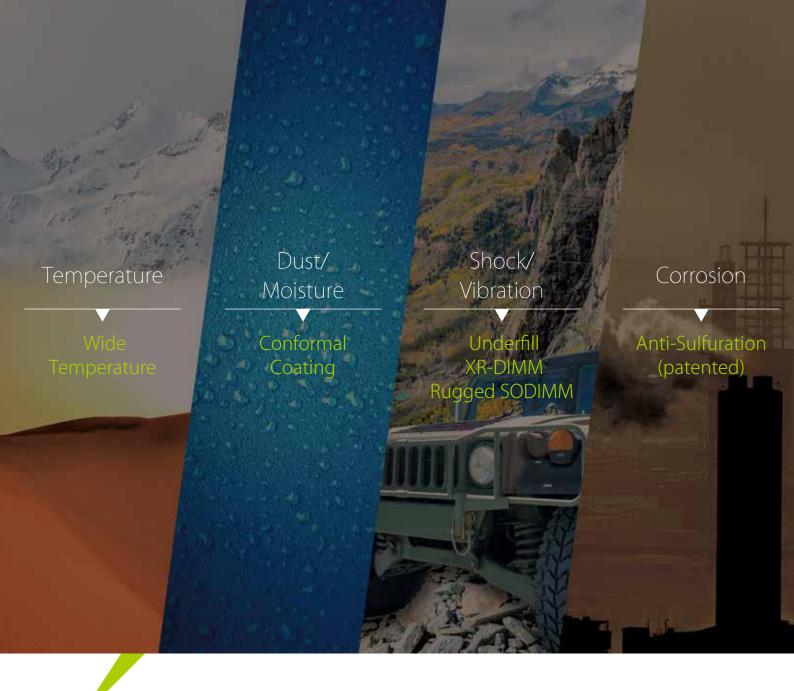
- Fixed BOM solution
- Longevity of supply, EOL & LTB notice
- Manufacturing in Taiwan protects IP

Professional Technique

- Strong HW/FW engineering know-how
- Customized design with a variety of solutions
- State-of-the-art technology

Trustworthy Supplier

- A global-scale service and maintenance system
- Responsive local FAE technical support
- 24/7 flexible and quick delivery service
- Complete RMA system



Solutions for Extreme Environments

Nowadays, as industrial memory products have been widely used in various kinds of applications, the need for memory modules that can maintain highly stable operating performance in harsh conditions is remarkably increasing.

As an industrial solution veteran and leading memory brand, Apacer always takes an outside-in perspective and strives for new breakthroughs, providing many value-added solutions and technologies for extreme environments to ensure product reliability, stability and durability.

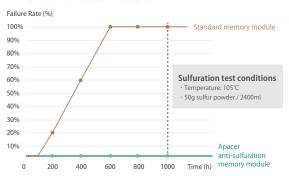
Technologies and Advantages



Apacer's patented anti-sulfuration memory modules replace standard silver electrodes with an exclusive alloy which has passed the ASTM B809-95 anti-sulfuration test.

- World's first anti-sulfuration memory modules
- Solve corrosion problems effectively and increase overall system lifespan

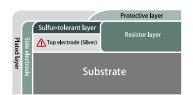
Anti-sulfuration test



Anti-sulfuration technology comparison

Apacer's advanced anti-sulfuration technology Method Adopts exclusive and improved alloy materials replace normal electrode Advantages / Reliable anti-sulfuration performance, improved product reliability and durability Reliable anti-sulfuration performance due to process failure





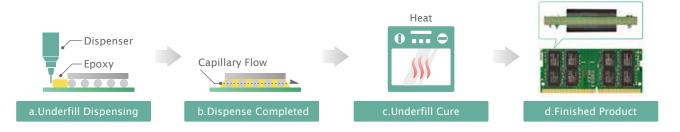


Underfill

Apacer provides underfill technology to increase product reliability and resistance to various thermal and mechanical shocks, ensuring that products continue to operate normally in high vibration and under extreme changes in environmental temperature.



- Strengthens the solder joints between solder balls and printed circuit board
- Increases the product's resistance against shock and vibration
- Reduces thermal stress damage
- Complies with MIL-STD-810G shock and vibration requirements
- Increases product reliability and lifespan

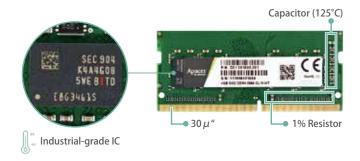


Wide Temperature Wide Temperature

Especially designed for harsh climates and special environmental conditions.

- Operating temperature range: -40 °C ≤ TC ≤ 85°C
- All industrial-grade components (DRAM, PCB, resistors and capacitors) ensure stability and reliability
- High/Low temp. test / Temp. cycling test
- Power cycling test

Insists on using industrial-grade DRAM ICs



Apacer's strengths of wide temperature memory

Apacer industrial-grade wide temp. memory		Standard memory (Commercial)
Industrial-grade (-40 ~ +85°C) Suitable for extreme high and low temperature environment	■ DRAM	Commercial-grade (0 ~ +85°C)
$30\mu^{\prime\prime}$ Avoids gold finger oxidation and ensures the stability of signal transmission	■ PCB plating thickness ▶	3μ"
Up to +125°C Ensures more stable voltage supply in high-temperature environment	Capacitor temp. specification	+85°C
± 1% tolerance Increases circuit stability and durability	■ Resistor specification ▶	\pm 5% tolerance





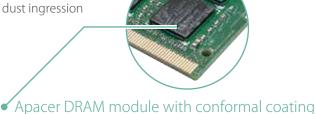
30μGold Finger

With the 30μ gold plating, the connector interface is more reliable and can withstand the potential damages in industrial applications.



Enhances reliability of products by applying coatings on the surface of printed circuit boards. The protective film can safeguard devices from dust ingression and liquid immersion.

- Uses automated spraying to maintain precise coating thickness
- Enhances product reliability
- Prolongs DRAM modules' lifespan





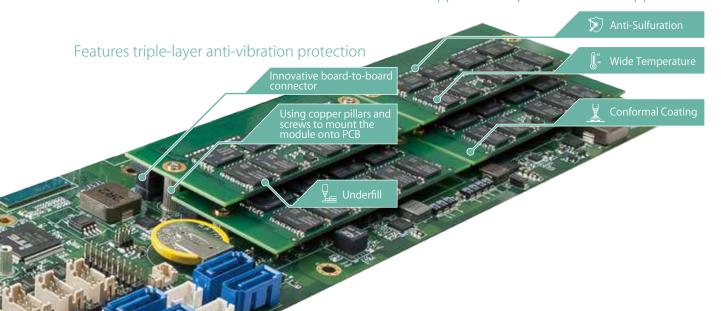
Extremely Rugged XR-DIMM

- Innovative board-to-board connector design
- Adopts highly durable 300-pin connector and mounting holes to improve the anti-vibration and anti-shock reliability
- Dual anti-shock and vibration certification: RTCA DO-160G / MIL-STD-810G
- Supports multiple protection technologies and value-added applications

Rugged Memory Comparison

	XR-DIMM Rugged Memory	Onboard memory
Anti-shock & anti-vibration ability	Great	Great
Memory upgradability	Yes	No
Repair difficulty	Easy	Difficult
RMA cost	Low	High
Stackable design	Yes	No
Motherboard space usage	Flexible	Uniform and inflexible

Supports multiple value-added applications



Embedded

UDIMM (Unbuffered DIMM)

- · JEDEC-compliant design
- Applicable for desktop computers, industrial computers and embedded systems

	America	2000 /= 12	000037==-	1040A R	- Alberta
Model	DDR5 UDIMM	DDR4 UDIMM	DDR3 UDIMM	DDR2 UDIMM	DDR UDIMM
Module Type	UDIMM	UDIMM	UDIMM	UDIMM	UDIMM
Memory Technology	DDR5	DDR4	DDR3	DDR2	DDR
Frequency	4800/5600	2133/2400/2666 2933/3200	1066/1333/1600/1866	533/667/800	266/333/400
Density	8G/16G/32G	2G/4G/8G/16G/32G	1G/2G/4G/8G/16G	1G/2G/4G	512M/1G
Voltage	1.1v	1.2v	1.5v/1.35v	1.8v	2.5v/2.6v
Pin Count	288-Pin	288-Pin	240-Pin	240-Pin	184-Pin
Width	64-Bit	64-Bit	64-Bit	64-Bit	64-Bit
PCB Height	1.23"	1.23"	1.18"	1.18"	1.25"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TA=0°C to 70°C
Application	Gaming / Healthcare / IoT / Factory Automation				
Value-Added	Underfill Conformal Coating	Underfill Continued Continued	Underfill Costing	Underfill Conformal Costing	Conformal Coating

SODIMM (Small Outline DIMM)

- JEDEC-compliant design
- Applicable for space-constraint systems, such as notebook computers, small-size industrial computers and embedded systems











DDR5 SODIMM	DDR4 SODIMM	DDR3 SODIMM	DDR2 SODIMM	DDR SODIMM
SODIMM	SODIMM	SODIMM	SODIMM	SODIMM
DDR5	DDR4	DDR3	DDR2	DDR
4800/5600	2133/2400/2666 2933/3200	1066/1333/1600/1866	533/667/800	266/333/400
8G/16G/32G	2G/4G/8G/16G/32G	1G/2G/4G/8G/16G	1G/2G/4G	512M/1G
1.1v	1.2v	1.5v/1.35v	1.8v	2.5v/2.6v
262-Pin	260-Pin	204-Pin	200-Pin	200-Pin
64-Bit	64-Bit	64-Bit	64-Bit	64-Bit
1.18"	1.18"	1.18"	1.18"	1.25"
TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TA=0°C to 70°C
Gaming / IoT / Transportation / Factory Automation				
	SODIMM DDR5 4800/5600 8G/16G/32G 1.1v 262-Pin 64-Bit 1.18"	SODIMM SODIMM DDR5 DDR4 4800/5600 2133/2400/2666 2933/3200 8G/16G/32G 2G/4G/8G/16G/32G 1.1v 1.2v 262-Pin 260-Pin 64-Bit 64-Bit 1.18" 1.18" TC=0°C to 85°C TC=0°C to 85°C	SODIMM SODIMM SODIMM DDR5 DDR4 DDR3 4800/5600 2133/2400/2666 2933/3200 1066/1333/1600/1866 8G/16G/32G 2G/4G/8G/16G/32G 1G/2G/4G/8G/16G 1.1v 1.2v 1.5v/1.35v 262-Pin 260-Pin 204-Pin 64-Bit 64-Bit 64-Bit 1.18" 1.18" 1.18" TC=0°C to 85°C TC=0°C to 85°C TC=0°C to 85°C	SODIMM SODIMM SODIMM SODIMM DDR5 DDR4 DDR3 DDR2 4800/5600 2133/2400/2666 2933/3200 1066/1333/1600/1866 533/667/800 8G/16G/32G 2G/4G/8G/16G/32G 1G/2G/4G/8G/16G 1G/2G/4G 1.1v 1.2v 1.5v/1.35v 1.8v 262-Pin 260-Pin 204-Pin 200-Pin 64-Bit 64-Bit 64-Bit 64-Bit 1.18" 1.18" 1.18" 1.18" TC=0°C to 85°C TC=0°C to 85°C TC=0°C to 85°C TC=0°C to 85°C





















Server/Workstation

RDIMM (ECC Registered DIMM)

- Includes a register to enhance clock, command and control signals
- Supports ECC error detection and correction
- Supports a built-in temperature-monitoring thermal sensor
- · Applicable for enterprise servers and cloud data centers

	manus Trougs	030 Jan 20	8 48 67 = 12
Model	DDR5 RDIMM	DDR4 RDIMM	DDR3 RDIMM
Module Type	RDIMM	RDIMM	RDIMM
Memory Technology	DDR5	DDR4	DDR3
Frequency	4800	2133/2400/2666/2933/3200	1066/1333/1600/1866
Density	16G/32G/64G/128G	4G/8G/16G/32G/64G/128G	4G/8G
Voltage	1.1v	1.2v	1.5v/1.35v
Pin Count	288-Pin	288-Pin	240-Pin
Width	80-Bit	72-Bit	72-Bit
PCB Height	1.23"	1.23"	1.18"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C
Application	Healthcare / Server & Networking		

LRDIMM (Load Reduced DIMM)

- · Includes a register to enhance clock, command and control signals
- \cdot Enhanced data signal with placing data buffer
- · Supports ECC error detection and correction
- · Supports a built-in temperature-monitoring thermal sensor
- · Applicable for enterprise servers and cloud data centers



Model	DDR4 LRDIMM	
Module Type	LRDIMM	
Memory Technology	DDR4	
Frequency	2666/2933/3200	
Density	64G/128G	
Voltage	1.2v	
Pin Count	288-Pin	
Width	72-Bit	
PCB Height	1.23"	
Operation Temperature	TC=0°C to 85°C	
Application	Healthcare / Server & Networking	









Server/Workstation

ECC UDIMM (ECC Unbuffered DIMM)

- · Supports ECC error detection and correction
- · Supports a built-in temperature-monitoring thermal sensor
- · Applicable for servers and workstations that require highly stable operation

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Model	DDR5 ECC UDIMM	DDR4 ECC UDIMM	DDR3 ECC UDIMM	DDR2 ECC UDIMM
Module Type	ECC UDIMM	ECC UDIMM	ECC UDIMM	ECC UDIMM
Memory Technology	DDR5	DDR4	DDR3	DDR2
Frequency	4800/5600	2133/2400/2666/2933/3200	1066/1333/1600/1866	533/667/800
Density	16G/32G	4G/8G/16G/32G	2G/4G/8G/16G	1G/2G/4G
Voltage	1.1v	1.2v	1.5v/1.35v	1.8v
Pin Count	288-Pin	288-Pin	240-Pin	240-Pin
Width	72-Bit	72-Bit	72-Bit	72-Bit
PCB Height	1.23"	1.23"	1.18"	1.18"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C
Application		Healthcare / IoT / Server & Netv	voking / Factory Automation	١
Value-Added	Thomas Sensor Case Figure Unident County	Thermal Gad Finger Underfill Control County	Thermal Gald Frequer Linderful Casting	Gold Finger Linderfall Cooling

ECC SODIMM (ECC Small Outline DIMM)

- · Supports ECC error detection and correction
- · Supports a built-in temperature-monitoring thermal sensor
- · Applicable for microservers, workstations, networking platforms and embedded systems



Server/Workstation

SORDIMM (Small Outline ECC Registered DIMM)

- · Achieves signal synchronization and stability with the use of a register
- Supports ECC error detection and correction
- Supports a built-in temperature-monitoring thermal sensor
- · Applicable for small-sized microserver and networking equipment, such as switches and routers



Model	DDR4 SORDIMM	
Module Type	(VLP) SORDIMM	
Memory Technology	DDR4	
Frequency	2133/2400/2666	
Density	4G/8G/16G	
Voltage	1.2v	
Pin Count	260-Pin	
Width	72-Bit	
PCB Height	0.738"/1.18"	
Operation Temperature	TC=0°C to 85°C	
Application	Server & Networking	

Value-Added



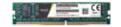






VLP Mini RDIMM / VLP Mini ECC UDIMM

- · Supports a built-in temperature-monitoring thermal sensor
- · High capacity, high performance and high stability
- · Supports ECC error detection and correction
- · Measures only 80mm long
- · Applicable for space-constrained networking, communication, server and embedded system





Model	DDR4 Mini RDIMM DDR4 VLP Mini ECC UDIMM		
Module Type	(VLP) Mini RDIMM	VLP Mini ECC UDIMM	
Memory Technology	DDR4	DDR4	
Frequency	2133/2400/2666 2133/2400/2666		
Density	4G/8G/16G	4G/8G/16G	
Voltage	1.2v	1.2v	
Pin Count	288-Pin	288-Pin	
Width	72-Bit	72-Bit	
PCB Height	0.738"/1.23"	0.738"	
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	
Application	Server & Networking	Server & Networking	

















Very Low Profile

VLP UDIMM (Very Low Profile Unbuffered DIMM)

- · Measures only 0.72~0.738-inch in height
- Prevents mechanical issues, and improves heat dissipation
- · Applicable for space-constrained systems, such as small-size industrial computers and embedded systems

	TINGS IN THE WAY	P. a. (4)	1000011		
Model	DDR5 VLP UDIMM	DDR4 VLP UDIMM	DDR3 VLP UDIMM	DDR2 VLP UDIMM	
Module Type	VLP UDIMM	VLP UDIMM	VLP UDIMM	VLP UDIMM	
Memory Technology	DDR5	DDR4	DDR3	DDR2	
Frequency	4800/5600	2133/2400/2666/2933/3200	1066/1333/1600	533/667/800	
Density	16G/32G	4G/8G/16G/32G	1G/2G/4G/8G	1G/2G/4G	
Voltage	1.1v	1.2v	1.5v/1.35v	1.8v	
Pin Count	288-Pin	288-Pin	240-Pin	240-Pin	
Width	64-Bit	64-Bit	64-Bit	64-Bit	
PCB Height	0.738"	0.738"	0.738"	0.72"	
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	
Application	IoT / Server & Networking				
Value-Added	Underfill Contornal Coasting	Underfill Contornal Country	Underfill Conformal Coating	Underfill Coating	

VLP SODIMM (Very Low Profile SODIMM) / VLP ECC SODIMM (Very Low Profile ECC SODIMM)

- · Measures only 0.7~0.709-inch in height
- · Saves up to 40% board space
- · Applicable for space-constrained systems, such as small form-factor industrial computers and embedded systems



Very Low Profile

VLP RDIMM (Very Low Profile Registered DIMM)

- · Measures only 0.738-inch in height
- Prevents mechanical issues, and improves heat dissipation
- · Supports ECC error detection and correction
- · Supports a built-in temperature-monitoring thermal sensor
- Applicable for space-constrained systems and systems that require high stability, such as blade servers, 1U rack servers and various embedded systems.

	INDOOR == u (P		
Model	DDR4 VLP RDIMM	DDR3 VLP RDIMM	
Module Type	VLP RDIMM	VLP RDIMM	
Memory Technology	DDR4	DDR3	
Frequency	2133/2400/2666/2933/3200	1066/1333/1600	
Density	4G/8G/16G/32G	1G/2G/4G/8G	
Voltage	1.2v	1.5v/1.35v	
Pin Count	288-Pin	240-Pin	
Width	72-Bit	72-Bit	
PCB Height	0.738"	0.738"	
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	
Application	Healthcare / Server & Networking		
Value-Added	Thermal Gold Flour	Thermal Gold Reserve	

VLP ECC UDIMM (Very Low Profile ECC Unbuffered DIMM)

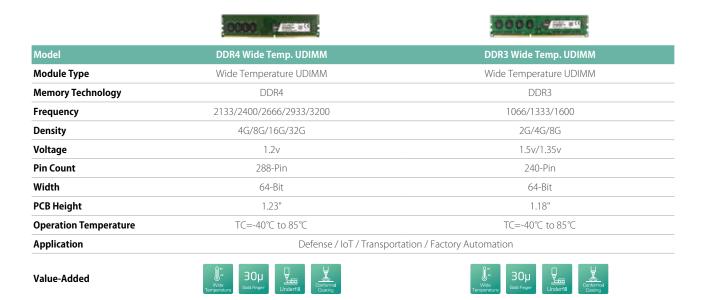
- · Measures only 0.738-inch in height
- Prevents mechanical issues, and improves heat dissipation
- Supports ECC error detection and correction
- · Supports a built-in temperature-monitoring thermal sensor
- · Applicable for space-constrained, servers and workstations that require high stability

		121-14000	00000 J == 100000
Model	DDR5 VLP ECC UDIMM	DDR4 VLP ECC UDIMM	DDR3 VLP ECC UDIMM
Module Type	VLP ECC UDIMM	VLP ECC UDIMM	VLP ECC UDIMM
Memory Technology	DDR5	DDR4	DDR3
Frequency	4800/5600	2133/2400/2666/2933/3200	1066/1333/1600
Density	16G/32G	4G/8G/16G/32G	1G/2G/4G/8G
Voltage	1.1v	1.2v	1.5v/1.35v
Pin Count	288-Pin	288-Pin	240-Pin
Width	72-Bit	72-Bit	72-Bit
PCB Height	0.738"	0.738"	0.738"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C
Application		Healthcare / Server & Networking	

Wide Temperature

Wide Temp UDIMM (Wide Temperature UDIMM)

- · Able to operate in temperatures ranging from -40°C to 85°C
- · Uses industrial-grade SDRAM components
- · With 30u gold plating PCB to improve anti-oxidation and ensure stability of signal transmission
- · Applicable for industrial, defense, aeronautical and vehicular systems that face extreme environmental challenges



Wide Temp SODIMM (Wide Temperature SODIMM)

- Able to operate in temperatures ranging from -40°C to 85°C
- · Uses industrial-grade SDRAM components
- With 30u gold plating PCB to improve anti-oxidation and ensure stability of signal transmission
- · Applicable for industrial, defense, aeronautical and vehicular systems that face extreme environmental challenges



Wide Temperature

Wide Temp ECC UDIMM (Wide Temperature ECC UDIMM)

- · Able to operate in temperatures ranging from -40 $^{\circ}$ C to 85 $^{\circ}$ C
- Uses industrial-grade SDRAM components
- With 30u gold plating PCB to improve anti-oxidation and ensure stability of signal transmission
- · Applicable for industrial, defense, aeronautical and vehicular systems that face extreme environmental challenges





Model	DDR4 Wide Temperature ECC UDIMM	DDR3 Wide Temperature ECC UDIMM	
Module Type	Wide Temperature ECC UDIMM	Wide Temperature ECC UDIMM	
Memory Technology	DDR4	DDR3	
Frequency	2133/2400/2666/2933/3200	1066/1333/1600	
Density	4G/8G/16G/32G	2G/4G/8G	
Voltage	1.2v 1.5v/1.35v		
Pin Count	288-Pin	240-Pin	
Width	72-Bit 72-Bit		
PCB Height	1.23"	1.18"	
Operation Temperature	TC=-40°C to 85°C	TC=-40°C to 85°C	
Application	Defense / IoT / Transportation / Factory Automation		
Value-Added	Wide Temperature Gold Finger Thormal Sensor Underfill Cooling	Wide Temperature Gold Finger Thormal Sensor Underful Cooting	

Wide Temp ECC SODIMM (Wide Temperature ECC SODIMM)

- · Able to operate in temperatures ranging from -40°C to 85°C
- Uses industrial-grade SDRAM components
- With 30u gold plating PCB to improve anti-oxidation and ensure stability of signal transmission
- · Applicable for industrial, defense, aeronautical and vehicular systems that face extreme environmental challenges





Model	DDR4 Wide Tempe. ECC SODIMM	DDR3 Wide Tempe. ECC SODIMM	
Module Type	Wide Temperature ECC SODIMM	Wide Temperature ECC SODIMM	
Memory Technology	DDR4	DDR3	
Frequency	2133/2400/2666/2933/3200	1066/1333/1600	
Density	4G/8G/16G/32G	2G/4G/8G	
Voltage	1.2v	1.5v/1.35v	
Pin Count	260-Pin	204-Pin	
Width	72-Bit 72-Bit		
PCB Height	eight 1.18" 1.11		
Operation Temperature	TC=-40°C to 85°C	TC=-40°C to 85°C	
Application	Defense / IoT / Transportation / Factory Automation		





















Anti-Sulfuration (Apacer Patented)

Anti-Sulfuration Memory Modules

- World's first anti-sulfuration memory modules for the sulfur-containing environment
- The innovative design is now patented
- Applicable for equipment exposed in highly contaminated environment and electronic equipment used in areas of high-concentration sulfur gas

	SOME TOWER	0000	# 100 E 10 S	A SUS
Model	DDR5 Anti-Sulfuration UDIMM	DDR4 Anti-Sulfuration UDIMM	DDR5 Anti-Sulfuration SODIMM	DDR4 Anti-Sulfuration SODIMM
Module Type	Anti-Sulfuration UDIMM	Anti-Sulfuration UDIMM	Anti-Sulfuration SODIMM	Anti-Sulfuration SODIMM
Memory Technology	DDR5	DDR4	DDR5	DDR4
Frequency	4800/5600	2133/2400/2666/2933/3200	4800/5600	2133/2400/2666/2933/3200
Density	8G/16G/32G	4G/8G/16G/32G	8G/16G/32G	4G/8G/16G/32G
Voltage	1.1v	1.2v	1.1v	1.2v
Pin Count	288-Pin	288-Pin	262-Pin	260-Pin
Width	64-Bit	64-Bit	64-Bit	64-Bit
PCB Height	1.23"	1.23"	1.18"	1.18"
Operation Temperature	TC=0°C to 85°C	TC=0℃ to 85℃	TC=0°C to 85°C	TC=0°C to 85°C / -40°C to 85°C
Application		Defense / Healthcare / IoT / Tran	sportation / Factory Automation	
Value-Added	30µ Underful Costing	30µ Cod Finger Underfill Conformat Coding	BOU Conformat Country	30µ

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Model	DDR5 Anti-Sulfuration RDIMM	DDR4 Anti-Sulfuration RDIMM	DDR5 Anti-Sulfuration ECC UDIMM	DDR4 Anti-Sulfuration ECC UDIMM	DDR5 Anti-Sulfuration ECC SODIMM	DDR4 Anti-Sulfuration ECC SODIMM
Module Type	Anti-Sulfuration RDIMM	Anti-Sulfuration RDIMM	Anti-Sulfuration ECC UDIMM	Anti-Sulfuration ECC UDIMM	Anti-Sulfuration ECC SODIMM	Anti-Sulfuration ECC SODIMM
Memory Technology	DDR5	DDR4	DDR5	DDR4	DDR5	DDR4
Frequency	4800	2133/2400/2666/ 2933/3200	4800/5600	2133/2400/2666/ 2933/3200	4800/5600	2133/2400/2666/ 2933/3200
Density	16G/32G	4G/8G/16G/32G	16G/32G	4G/8G/16G/32G	16G/32G	4G/8G/16G/32G
Voltage	1.1v	1.2v	1.1v	1.2v	1.1v	1.2v
Pin Count	288-Pin	288-Pin	288-Pin	288-Pin	262-Pin	260-Pin
Width	80-Bit	72-Bit	72-Bit	72-Bit	72-Bit	72-Bit
PCB Height	1.23"	1.23"	1.23"	1.23"	1.18"	1.18"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C
Application	Defense / Healthcare / IoT / Transportation / Factory Automation					
Value-Added	Thermal Sensor Gold Finger	Thermal Sensor	Tharmol Service Gold Finger	Thornal Sensor Gold Finger	Thermal Gold Finger	Thermal Gold Finger

Rugged Memory

Rugged SODIMM

- Designed with two mounting holes to secure the memory module to the board to achieve shock and vibration resistance
- Dual anti-shock and vibration certification: RTCA DO-160G / MIL-STD-883K
- · Applicable for transportation, automation, wind power geneation, energy, defense and aeronautical equipment that requires shock and vibration resistance



Model	DDR4 Rugged SODIMM	
Module Type	Rugged SODIMM	
Memory Technology	DDR4	
Frequency	2133/2400/2666/2933/3200	
Density	8G/16G/32G	
Voltage	1.2v	
Pin Count	260-Pin	
Width	64-Bit/72-Bit	
PCB Height	1.377"	
Operation Temperature	TC=0°C to 85°C / -40°C to 85°C	
Application	Defense / Transportation	
Value-Added	30u	

Value-Added







XR-DIMM

- · Designed for shock and vibration environments
- Innovative design with highly rugged 300-pin connector and mounting holes
- Dual anti-shock and vibration certification: RTCA DO-160G / MIL-STD-810G
- · Improves the stability of signal transmission
- · Applicable for transportation, defense and aeronautical equipment that requires shock and vibration resistance



Model	DDR4 XR-DIMM	
Module Type	XR-DIMM	
Memory Technology	DDR4	
Frequency	2133/2400	
Density	8G/16G	
Voltage	1.2v	
Pin Count	300-Pin	
Width	72-Bit	
PCB Height	1.466"	
Operation Temperature	TC=-40°C to 85°C	
Application	Defense / Transportation	









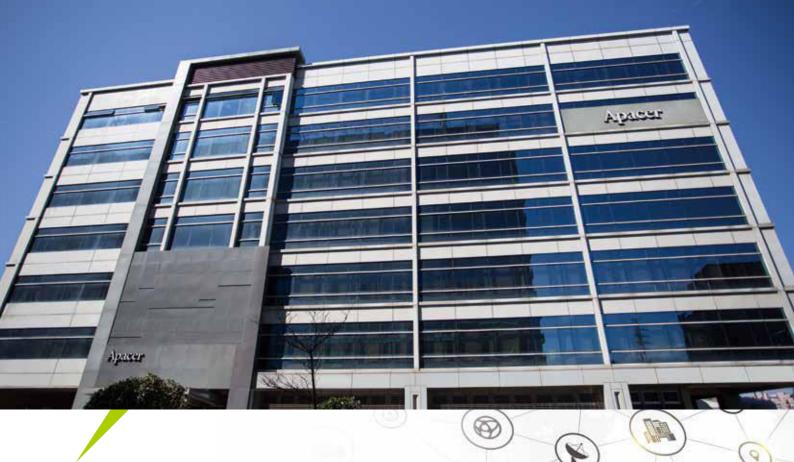


Fully Lead-Free

Fully Lead-Free Memory Module

- The world's first Fully Lead-Free memory module, surpassing RoHS environmental standards.
- Fully compliant with RoHS standards, no RoHS exemptions required
- Uses Fully Lead-Free Resistors without RoHS 7(c)-I exemption
- Meeting the market demand for environmentally friendly products

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Model	DDR5 Fully lead-free UDIMM	DDR5 Fully lead-free SODIMM	DDR5 Fully lead-free RDIMM	DDR5 Fully lead-free ECC UDIMM	DDR5 Fully lead-free ECC SODIMM
Module Type	Fully lead-free UDIMM	Fully lead-free SODIMM	Fully lead-free RDIMM	Fully lead-free ECC UDIMM	Fully lead-free ECC SODIMM
Memory Technology	DDR5	DDR5	DDR5	DDR5	DDR5
Frequency	4800/5600	4800/5600	4800	4800/5600	4800/5600
Density	8G/16G/32G	8G/16G/32G	16G/32G	16G/32G	16G/32G
Voltage	1.1v	1.1v	1.1v	1.1v	1.1v
Pin Count	288-Pin	262-Pin	288-Pin	288-Pin	262-Pin
Width	64-Bit	64-Bit	80-Bit	72-Bit	72-Bit
PCB Height	1.23"	1.18"	1.23"	1.23"	1.18"
Operating Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C
Application	Gaming / Healthcare / IoT / Factory Automation	Gaming / IoT / Transportation / Factory Automation	Healthcare / Server & Networking	Healthcare / IoT / Server & Netwoking / Factory Automation	loT / Server & Networking / Transportation / Factory Automation
Value-Added	Underfill Covinmel County	Underfill Corromatic Coates	Bound Bound Card Finger Underfill Underfill	Thermal Gardenger Underfill Controlling	Thermal Gold Finger Underfill Dizzen



About Apacer

Apacer is a global leader in digital storage solutions devoted to innovative storage technology and services. After 25 years in the industry, we remain dedicated to our belief in "persistence in doing the right things." Our core values, as always, continue to revolve around reliability and innovation.

The company focuses on embedded applications for a variety of vertical markets, including military, medical, gaming, and industrial, and has become an integration expert in digital storage, innovative applications, and value-added services. Apacer is known for its advanced technologies and product quality and was ranked by Gartner as the top industrial SSD supplier for five consecutive years, from 2012 to 2016. In addition, Apacer is committed to making a positive impact on societal issues and has joined the **Responsible Business Alliance (RBA)**, which is formerly known as Electronic Industry Citizenship Coalition (EICC), a coalition promoting **corporate social responsibility (CSR)** within the global electronics supply chain. We believe that the success of a corporation is marked not by profit but by how we benefit others, whether by caring for the environment or making contributions to society.

Compliance and Associations







Global Presence

Taiwan (Headquarters)

Apacer Technology Inc. Tel: +886-2-2267-8000 Fax: +886-2-2267-2261 Industrial@apacer.com

Europe

Apacer Technology B.V. Tel: +31-40-267-0000 Fax: +31-40-290-0686 sales@apacer.nl

Japan

Apacer Technology Corp. Tel: +81-3-5419-2668 Fax: +81-3-5419-0018 jpservices@apacer.com

India

Apacer Technologies Pvt. Ltd. Tel: +91-80-41529061~3 Fax: +91-80-41700215 sales_India@apacer.com

U.S.A.

Apacer Memory America, Inc. Tel: +1-408-518-8699 Fax: 1-510-249-9551 ssdsales@apacerus.com

Shanghai

Apacer Electronic(Shanghai) Co., Ltd. Tel: +86-21-6228-9939 Industrial@apacer.com

